L Number	Hits	Search Text	DB	Time stamp
1	0	packaging adj2 semiconductor adj die adj containing adj sensors	USPAT	2003/10/27 11:05
2	0	package and (semiconductor adj die adj containing adj sensors) and (annular adj interface)	USPAT	2003/10/27 11:07
3	0	package and sensor and (semiconductor adj die adj package) and (annular adj interface)	USPAT	2003/10/27 11:08
4	0	package and (semiconductor adj2 die adj containing adj sensors) and (annular adj interface)	USPAT	2003/10/27 11:07
6	2	package and sensor and (semiconductor adj die adj package) and interface and surface and area and pad and bond and ring	USPAT	2003/10/27 11:09
5	7	package and sensor and (semiconductor adj die adj package) and interface and surface and area	USPAT	2003/10/27 11:32
7	2831	257/666	USPAT	2003/10/27 11:32
8	597	257/667	USPAT	2003/10/27 11:32
9	1764	257/668	USPAT	2003/10/27 11:32
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11	1229	257/734	USPAT	2003/10/27 11:32
12	659	257/735	USPAT	2003/10/27 11:32
13	2328	257/737	USPAT	2003/10/27 11:32
14	2038	257/738	USPAT	2003/10/27 11:32
15	1717	257/777	USPAT	2003/10/27 11:32
16	2944	257/778	USPAT	2003/10/27 11:32
17	1126	257/779	USPAT	2003/10/27 11:33
18	1514	257/780	USPAT	2003/10/27 11:33
19	811	257/781	USPAT	2003/10/27 11:33
20	691	257/782	USPAT	2003/10/27 11:33
21	1161	257/783	USPAT	2003/10/27 11:33
22	1559	257/784	USPAT	2003/10/27 11:33
23	2278	257/787	USPAT	2003/10/27 11:33

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